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**DL PACKAGE** 

**SCAS825-JUNE 2006** 

#### **FEATURES**

- Member of the Texas Instruments Widebus™
   Family
- Operates From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 4.2 ns at 3.3 V
- Typical V<sub>OLP</sub> (Output Ground Bounce) <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot) >2 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V<sub>CC</sub>)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 1000-V Charged-Device Model (C101)

# DESCRIPTION/ ORDERING INFORMATION

This 16-bit transparent D-type latch is designed for 1.65-V to 3.6-V  $V_{\rm CC}$  operation.

The SN74LVC16373A is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. The device can be used as two 8-bit latches or one 16-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable  $(\overline{OE})$  input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

#### (TOP VIEW) 48 🛭 1LE 10E 47 🛮 1D1 1Q1 2 1Q2 🛮 3 46 🛮 1D2 GND 4 45 GND 1Q3 []5 44 🛮 1D3 1Q4 **[**]6 43 1D4 42 V<sub>CC</sub> $V_{CC}$ 1Q5 🛮 8 41 🛮 1D5 1Q6 🛮 9 40 1 1D6 GND 10 39 | GND 1Q7 11 38 🛮 1D7 1Q8 📙 12 37 1 1D8 2Q1 **1**3 36 L 2D1 14 35 2Q2 ll 2D2 GND 15 34 🛮 GND 2Q3 16 33 T 2D3 32 🛮 2D4 2Q4 L 17 31 [] V<sub>CC</sub> V<sub>CC</sub> **□** 18 2Q5 🛮 19 30 2D5 2Q6 []20 29 2D6 GND 21 28 GND 2Q7 []22 27 2D7 2Q8 [] 23 26 2D8 2<del>0Ε</del> Γ 24 25 **∏** 2LE

#### ORDERING INFORMATION

T <sub>A</sub>	PACKAGE <sup>(1</sup>	)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	SSOP - DL	Tape and reel	CLVC16373AMDLREP	LVC16373AMEP

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

**SCAS825-JUNE 2006** 



### **DESCRIPTION/ORDERING INFORMATION (CONTINUED)**

 $\overline{\text{OE}}$  does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

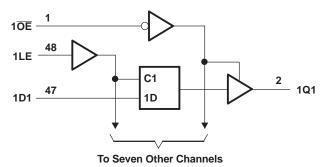
To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

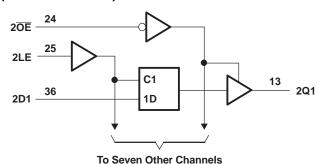
This device is fully specified for partial-power-down applications using  $I_{\text{off}}$ . The  $I_{\text{off}}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

#### **FUNCTION TABLE**

ı	NPUTS	3	OUTPUT
ŌΕ	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	$Q_0$
Н	Χ	Χ	Z

#### **LOGIC DIAGRAM (POSITIVE LOGIC)**







### SN74LVC16373A-EP 16-BIT TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

SCAS825-JUNE 2006

### Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range		-0.5	6.5	V
VI	Input voltage range (2)		-0.5	6.5	V
Vo	Voltage range applied to any output in the high-impedance or power-off state $^{(2)}$ —0.5 6.				V
Vo	Voltage range applied to any output in the	e high or low state (2)(3)	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		<b>-</b> 50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		<b>-</b> 50	mA
Io	Continuous output current			±50	mA
	Continuous current through each V <sub>CC</sub> or 0	GND		±100	mA
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>			63	°C/W
T <sub>stg</sub>	Storage temperature range <sup>(5)</sup>			150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V<sub>CC</sub> is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.
- (5) Long-term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep\_quality for additional information on enhanced plastic packaging.

### Recommended Operating Conditions<sup>(1)</sup>

			MIN	MAX	UNIT	
1/	Cumply voltage	Operating	1.65	3.6	V	
$V_{CC}$	Supply voltage	Data retention only	1.5		V	
		V <sub>CC</sub> = 1.65 V to 1.95 V	$0.65 \times V_{CC}$			
$V_{IH}$	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		V <sub>CC</sub> = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		V <sub>CC</sub> = 2.7 V to 3.6 V		0.8		
VI	Input voltage		0	5.5	V	
\/	Output voltage	High or low state	0	$V_{CC}$	V	
v <sub>O</sub>		High-impedance state		5.5	V	
		V <sub>CC</sub> = 1.65 V		-4		
	High level output ourrent	$V_{CC} = 2.3 \text{ V}$		-8	mA	
I <sub>OH</sub>	High-level output current	$V_{CC} = 2.7 \text{ V}$		-12	ША	
		$V_{CC} = 3 V$		-24		
		V <sub>CC</sub> = 1.65 V		4		
	Low level output current	$V_{CC} = 2.3 \text{ V}$		8	mA	
I <sub>OL</sub> Low-level out	Low-level output current	$V_{CC} = 2.7 \text{ V}$		12		
		$V_{CC} = 3 V$		24		
Δt/Δν	Input transition rise or fall rate			10	ns/V	
T <sub>A</sub>	Operating free-air temperature		-55	125	°C	

<sup>(1)</sup> All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

### **SN74LVC16373A-EP 16-BIT TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS**

SCAS825-JUNE 2006



#### **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TEST CONDITIONS		MIN	TYP <sup>(1)</sup> MAX	UNIT
	$I_{OH} = -100 \mu A$		1.65 V to 3.6 V	$V_{CC} - 0.2$		
	$I_{OH} = -4 \text{ mA}$	$_{OH}$ = -4 mA				
V	$I_{OH} = -8 \text{ mA}$		2.3 V	1.7		V
V <sub>OH</sub>	I <sub>OH</sub> = -12 mA		2.7 V	2.2		V
	1 <sub>OH</sub> = -12 IIIA		3 V	2.4		
	$I_{OH} = -24 \text{ mA}$		3 V	2.2		
	I <sub>OL</sub> = 100 μA		1.65 V to 3.6 V		0.2	
	I <sub>OL</sub> = 4 mA	I <sub>OL</sub> = 4 mA				
V <sub>OL</sub>	I <sub>OL</sub> = 8 mA		2.3 V		0.7	V
	I <sub>OL</sub> = 12 mA		2.7 V		0.4	
	I <sub>OL</sub> = 24 mA		3 V		0.55	
I <sub>I</sub>	V <sub>I</sub> = 0 to 5.5 V		3.6 V		±5	μΑ
I <sub>off</sub>	$V_I$ or $V_O = 5.5 \text{ V}$		0		±10	μΑ
I <sub>OZ</sub>	V <sub>O</sub> = 0 to 5.5 V		3.6 V		±10	μΑ
1	V <sub>I</sub> = V <sub>CC</sub> or GND	1 0	3.6 V		20	^
I <sub>CC</sub>	$3.6 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}^{(2)}$		3.0 V		20	μΑ
$\Delta I_{CC}$	One input at V <sub>CC</sub> – 0.6 V, Other inputs at \	CC or GND	2.7 V to 3.6 V		500	μΑ
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND				5	pF
Co	$V_O = V_{CC}$ or GND		3.3 V		6.5	pF

<sup>(1)</sup> All typical values are at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C. (2) This applies in the disabled state only.

### **Timing Requirements**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			$V_{CC}$ = 2.5 V $\pm$ 0.2 V		$V_{CC} = 2.7 \text{ V}$ $V_{CC} = 3.3 \text{ V}$ $\pm 0.3 \text{ V}$			UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>w</sub>	Pulse duration, LE high	3.3		3.3		3.3		ns
t <sub>su</sub>	Setup time, data before LE↓	1.7		1.7		1.7		ns
t <sub>h</sub>	Hold time, data after LE↓	1.6		1.6		1.6		ns

### **Switching Characteristics**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	V <sub>CC</sub> = 2 ± 0.2	2.5 V : V	V <sub>CC</sub> = 2	2.7 V	V <sub>CC</sub> = 3 ± 0.3	3.3 V V	UNIT
(INPUT)		(001701)	MIN	MAX	MIN	MAX	MIN	MAX	
	D	Q	1	5.2	1	4.9	1.6	4.2	20
t <sub>pd</sub>	LE	Q	1	5.2	1	5.3	1.3	4.6	ns
t <sub>en</sub>	ŌĒ	Q	1	7.7	1	6.2	1.3	5.3	ns
t <sub>dis</sub>	ŌĒ	Q	1	5.2	1	6.3	2.1	5.9	ns



# SN74LVC16373A-EP 16-BIT TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

SCAS825-JUNE 2006

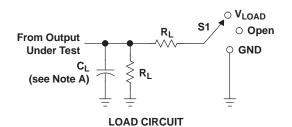
### **Operating Characteristics**

 $T_A = 25^{\circ}C$ 

	PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V TYP	V <sub>CC</sub> = 2.5 V TYP	V <sub>CC</sub> = 3.3 V TYP	UNIT
C	Power dissipation capacitance	Outputs enabled	f = 10 MHz	32	35	39	pF
$C_{pd}$	per latch	Outputs disabled	1 = 10 NIM2	4	4	6	þΓ

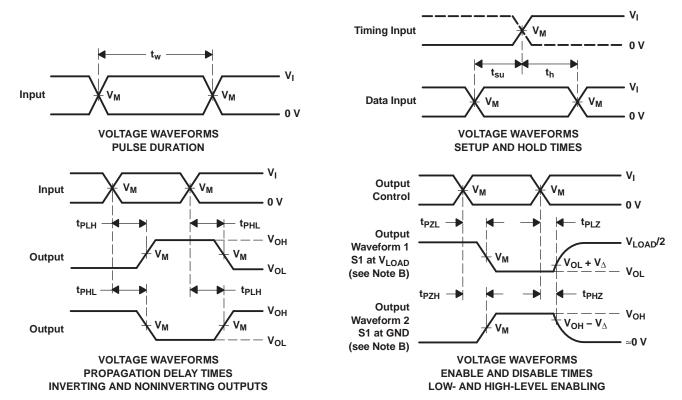


#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

.,	INF	PUTS	.,	.,		_	.,
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	R <sub>L</sub>	$V_{\Delta}$
2.5 V ± 0.2 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	50 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_{O} = 50 \Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

www.ti.com 11-Nov-2025

#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
CLVC16373AMDLREP	Active	Production	SSOP (DL)   48	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LVC16373AMEP
V62/06649-01XE	Active	Production	SSOP (DL)   48	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LVC16373AMEP

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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#### OTHER QUALIFIED VERSIONS OF SN74LVC16373A-EP:

Catalog: SN74LVC16373A

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



### **PACKAGE OPTION ADDENDUM**

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NOTE: Qualified Version Definitions:

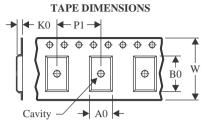
 $_{\bullet}$  Catalog - TI's standard catalog product

### **PACKAGE MATERIALS INFORMATION**

www.ti.com 23-Jul-2025

### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CLVC16373AMDLREP	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 23-Jul-2025

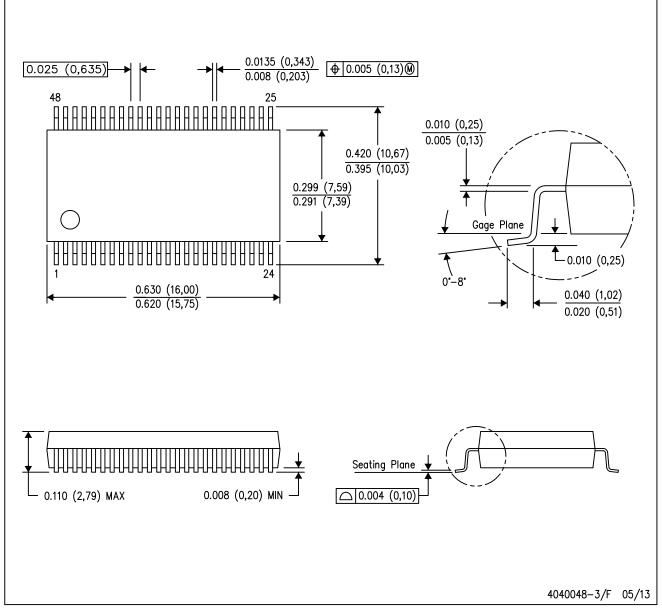


### \*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	CLVC16373AMDLREP	SSOP	DL	48	1000	356.0	356.0	53.0	

# DL (R-PDSO-G48)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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